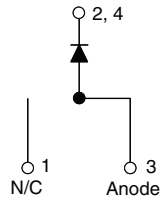


# HEXFRED<sup>®</sup>, Ultrafast Soft Recovery Diode, 4 A


**DPAK (TO-252AA)**

**FEATURES**

- Ultrafast recovery time
- Ultrasoft recovery
- Very low  $I_{RRM}$
- Very low  $Q_{rr}$
- Guaranteed avalanche
- Specified at operating temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	4 A
$V_R$	600 V
$V_F$ at $I_F$	1.4 V
$t_{rr}$ typ.	17 ns
$T_J$ max.	150 °C
Package	DPAK (TO-252AA)
Circuit configuration	Single

**BENEFITS**

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

**DESCRIPTION / APPLICATIONS**

These diodes are optimized to reduce losses and EMI / RFI in high frequency power conditioning systems. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for freewheeling, flyback, power converters, motor drives, and other applications where high speed and reduced switching losses are design requirements.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	$V_{RRM}$		600	V
Maximum continuous forward current	$I_{F(AV)}$	$T_C = 100\text{ °C}$	4	A
Single pulse forward current	$I_{FSM}$		25	
Repetitive peak forward current	$I_{FRM}$	$T_C = 116\text{ °C}$	16	
Maximum power dissipation	$P_D$	$T_C = 100\text{ °C}$	10	W
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +150	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage See fig. 1	$V_F$	$I_F = 4\text{ A}$	-	1.5	1.8	
		$I_F = 8\text{ A}$	-	1.8	2.2	
		$I_F = 4\text{ A}, T_J = 125\text{ °C}$	-	1.4	1.7	
Maximum reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.17	3.0	$\mu\text{A}$
		$T_J = 125\text{ °C}, V_R = 0.8 \times V_R$ rated	-	44	300	
Junction capacitance	$C_T$	$V_R = 200\text{ V}$	-	4	8	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	8.0	-	nH



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $dI_F/dt = 200\text{ A}/\mu\text{A}$ , $V_R = 30\text{ V}$	-	17	-	ns
		$T_J = 25\text{ }^\circ\text{C}$	-	28	42	
		$T_J = 125\text{ }^\circ\text{C}$	-	38	57	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	2.9	5.2	A
		$T_J = 125\text{ }^\circ\text{C}$	-	3.7	6.7	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	40	60	nC
		$T_J = 125\text{ }^\circ\text{C}$	-	70	105	
Rate of fall of recovery current	$dI_{(rec)M}/dt$	$T_J = 25\text{ }^\circ\text{C}$	-	280	-	A/ $\mu\text{s}$
		$T_J = 125\text{ }^\circ\text{C}$	-	235	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-55	-	150	$^\circ\text{C}$
Thermal resistance, junction to case	$R_{thJC}$		-	-	5.0	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to ambient	$R_{thJA}$	Typical socket mount	-	-	80	
Weight			-	2.0	-	g
			-	0.07	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style DPAK (TO-252AA)	HFA04SD60S			

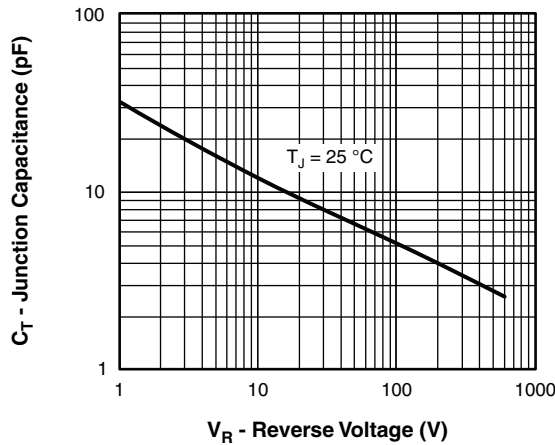
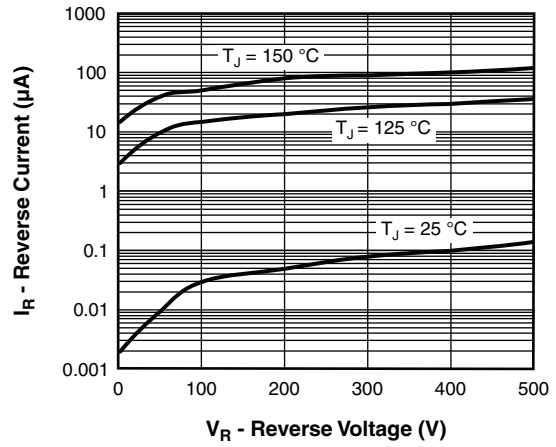
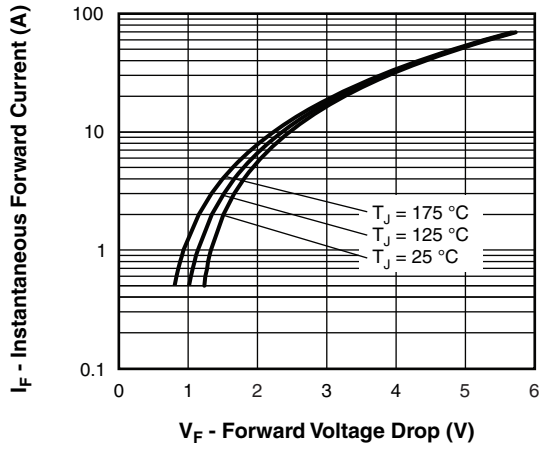


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

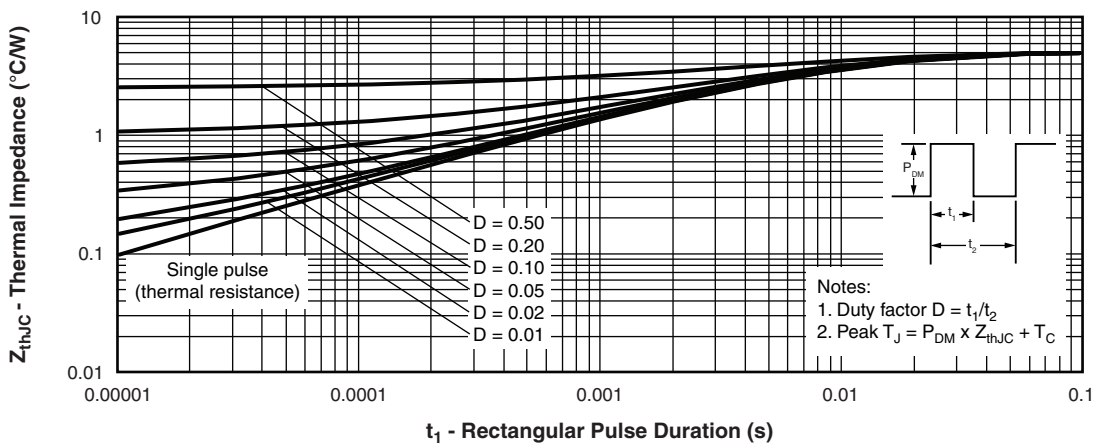


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

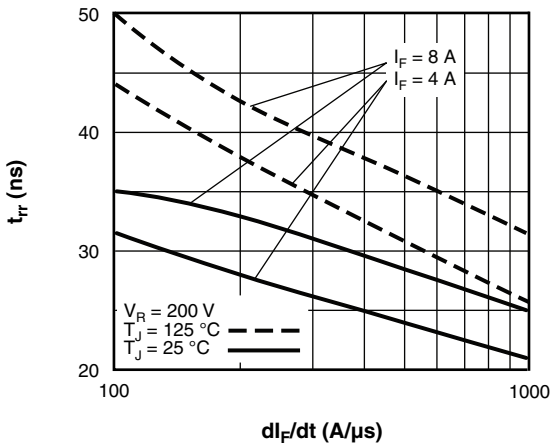


Fig. 5 - Typical Reverse Recovery Time vs.  $di_F/dt$

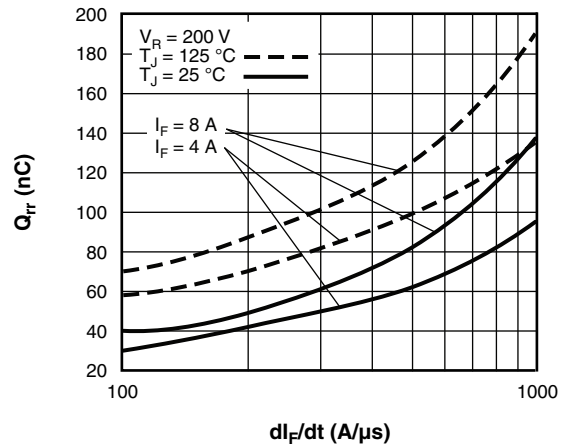


Fig. 7 - Typical Stored Charge vs.  $di_F/dt$

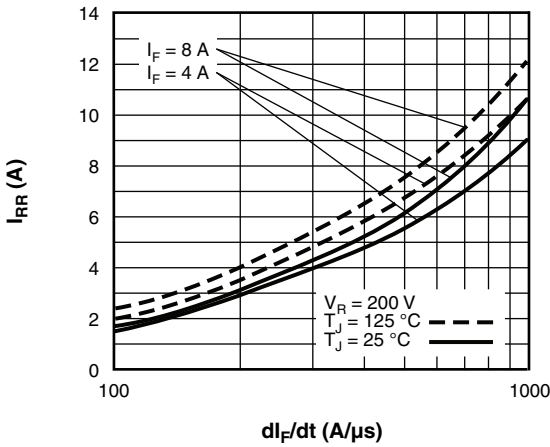


Fig. 6 - Typical Recovery Current vs.  $di_F/dt$

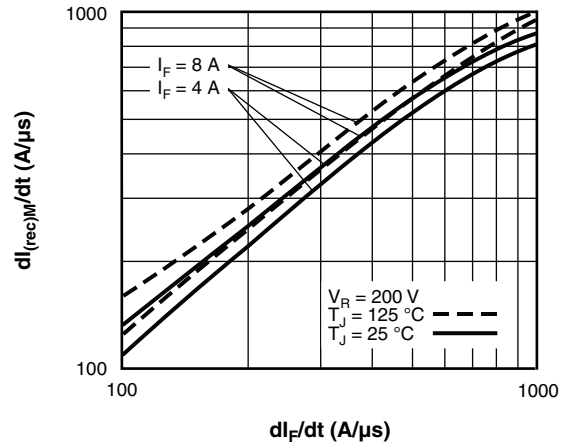


Fig. 8 - Typical  $di_{(rec)M}/dt$  vs.  $di_F/dt$

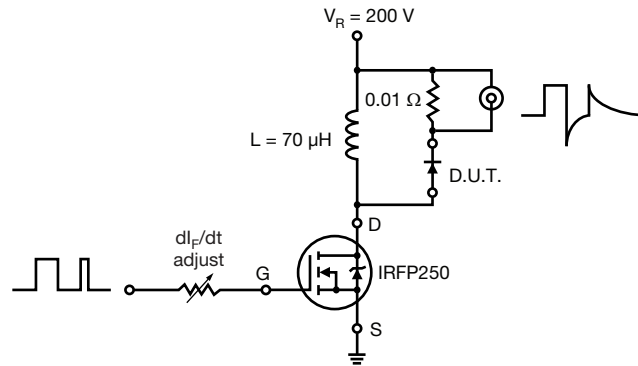


Fig. 9 - Reverse Recovery Parameter Test Circuit

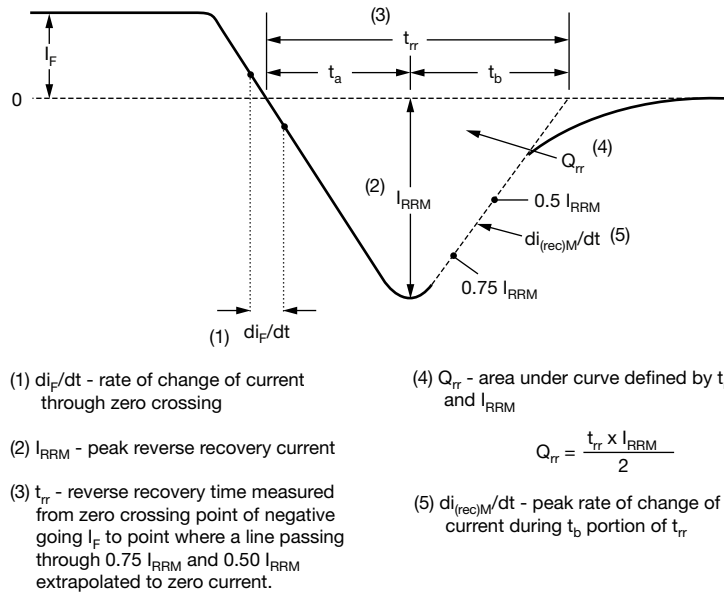
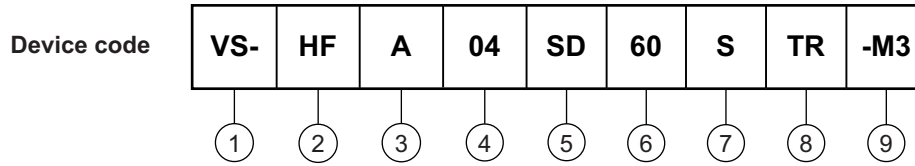


Fig. 10 - Reverse Recovery Waveform and Definitions



## ORDERING INFORMATION TABLE



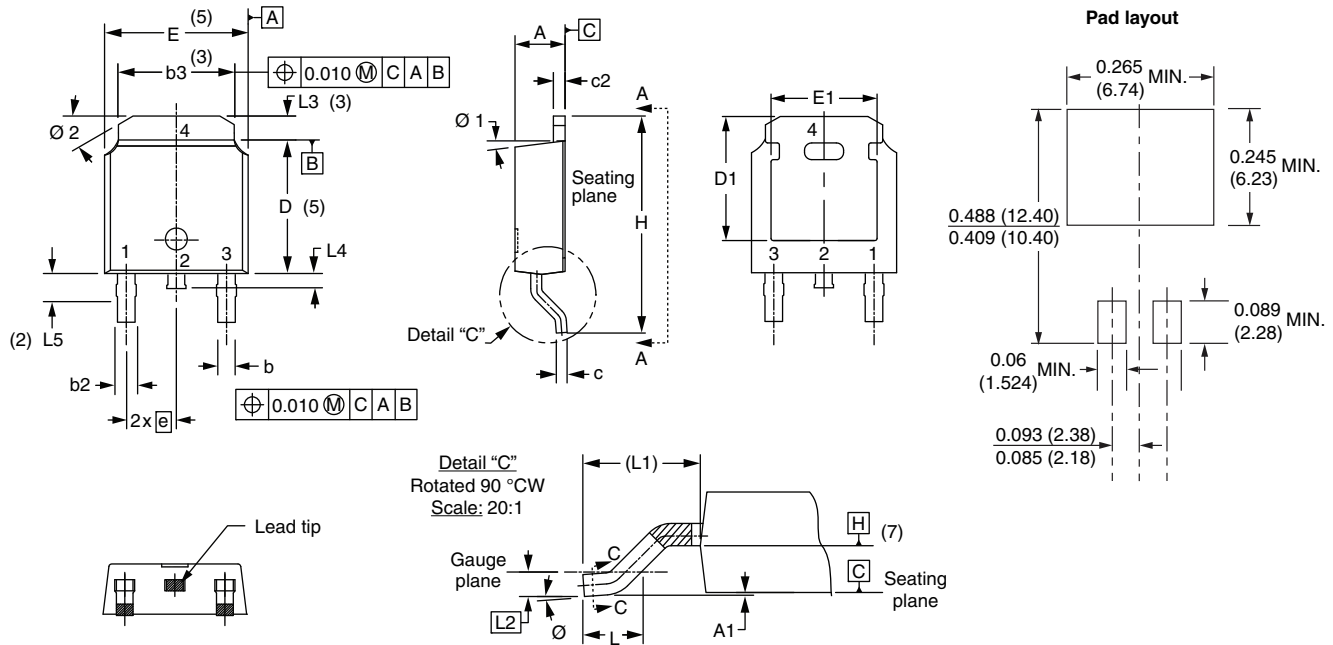
- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (04 = 4 A)
- 5** - D-PAK
- 6** - Voltage rating (60 = 600 V)
- 7** - S = D-PAK
- 8** -
  - TR = tape and reel
  - R = tape and reel (right oriented)
  - L = tape and reel (left oriented)
- 9** - Environmental digit:
  - M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA04SD60S-M3	75	3000	Antistatic plastic tube
VS-HFA04SD60STR-M3	2000	2000	13" diameter reel
VS-HFA04SD60SL-M3	3000	3000	13" diameter reel
VS-HFA04SD60SR-M3	3000	3000	13" diameter reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95627">www.vishay.com/doc?95627</a>
Part marking information	<a href="http://www.vishay.com/doc?95176">www.vishay.com/doc?95176</a>
Packaging information	<a href="http://www.vishay.com/doc?95033">www.vishay.com/doc?95033</a>

### D-PAK (TO-252AA) "M"

**DIMENSIONS** in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	2.18	2.39	0.086	0.094		e	2.29 BSC		0.090 BSC		
A1	-	0.13	-	0.005		H	9.40	10.41	0.370	0.410	
b	0.64	0.89	0.025	0.035		L	1.40	1.78	0.055	0.070	
b2	0.76	1.14	0.030	0.045		L1	2.74 BSC		0.108 REF.		
b3	4.95	5.46	0.195	0.215	3	L2	0.51 BSC		0.020 BSC		
c	0.46	0.61	0.018	0.024		L3	0.89	1.27	0.035	0.050	3
c2	0.46	0.89	0.018	0.035		L4	-	1.02	-	0.040	
D	5.97	6.22	0.235	0.245	5	L5	1.14	1.52	0.045	0.060	2
D1	5.21	-	0.205	-	3	Ø	0°	10°	0°	10°	
E	6.35	6.73	0.250	0.265	5	Ø1	0°	15°	0°	15°	
E1	4.32	-	0.170	-	3	Ø2	25°	35°	25°	35°	

**Notes**

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Section C - C dimension apply to the flat section of the lead between 0.13 and 0.25 mm (0.005 and 0.10") from the lead tip
- (5) Dimension D, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (6) Dimension b1 and c1 applied to base metal only
- (7) Datum A and B to be determined at datum plane H
- (8) Outline conforms to JEDEC® outline TO-252AA



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